

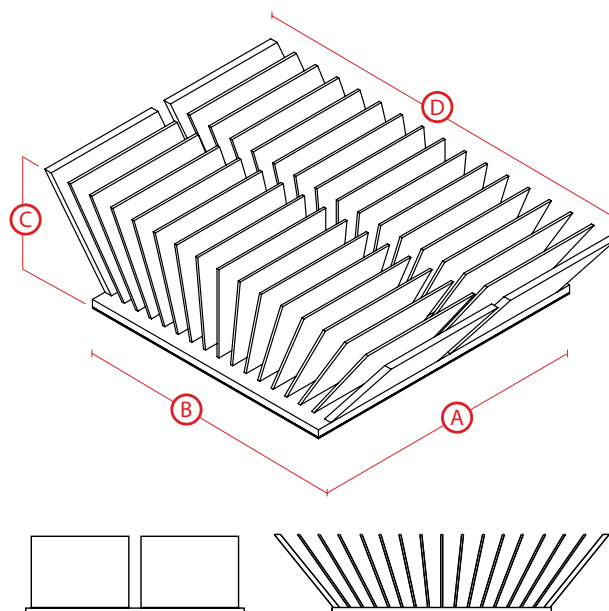


High Performance ASIC Cooling Solutions w/Thermal Tape Attachment

ATS PART # ATS-56009-C3-R0

Features & Benefits

- » maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » Designed specifically for ASIC package and their unique cooling requirements
- » Comes preassembled with high performance thermal interface material



**Image above is for illustration purposes only.*

Thermal Performance

AIR VELOCITY		THERMAL RESISTANCE	
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)
200	1.0	4.8	2.4
300	1.5	3.9	
400	2.0	3.1	
500	2.5	2.7	
600	3.0	2.4	
700	3.5	2.3	
800	4.0	2.2	

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
58 mm	30 mm	9 mm	44.3 mm	SAINT-GOBAIN C675	BLACK-ANODIZED

NOTES:

- 1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
- 2) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 3) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 4) Contact ATS to learn about custom options available.



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